

P2401

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Type of Project: New IEEE Standard

PAR Request Date: 23-Sep-2013

PAR Approval Date: 11-Dec-2013

PAR Expiration Date: 31-Dec-2017

Status: PAR for a New IEEE Standard

1.1 Project Number: P2401

1.2 Type of Document: Standard

1.3 Life Cycle: Full Use

2.1 Title: Standard Format for LSI-Package-Board Interoperable Design

3.1 Working Group: Standard Format for LSI-Package-Board Interoperable Design (C/DA/LPB)

Contact Information for Working Group Chair

Name: Yoshinori Fukuba

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Contact Information for Working Group Vice-Chair

None

3.2 Sponsoring Society and Committee: IEEE Computer Society/Design Automation (C/DA)

Contact Information for Sponsor Chair

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Contact Information for Standards Representative

None

4.1 Type of Ballot: Entity

4.2 Expected Date of submission of draft to the IEEE-SA for Initial Sponsor Ballot: 03/2015

4.3 Projected Completion Date for Submittal to RevCom: 08/2015

5.1 Approximate number of entities expected to be actively involved in the development of this project: 10

5.2 Scope: This standard defines a common interoperable format used for the design of (a) Large Scale Integrated (LSI) circuits, (b) Packages for such LSI circuits and (c) Printed Circuit Boards on which the packaged LSI circuits are interconnected. Collectively such designs are referred to as "LSI-Package-Board" designs. The format provides a common way to specify information/data about the project management, net lists, components, design rules, and geometries used in LSI-Package-Board designs.

5.3 Is the completion of this standard dependent upon the completion of another standard: No

5.4 Purpose: The general purpose of this standard is to develop a common format that LSI-Package-Board design tools can use to exchange information/data seamlessly, as opposed to having to work with multiple different input and output formats.

5.5 Need for the Project: Because techniques for the design of LSI circuits, packages and printed circuit boards evolved separately, the software used for such designs typically employ different formats even when accessing identical information and data. The use of these differing formats presents a barrier to the natural information flow between software tools used for LSI-Package-Board design. The common format to be standardized will eliminate this barrier, and achieve seamless information/data exchange between LSI-Package-Board software tools.

5.6 Stakeholders for the Standard: Electronic Design Automation (EDA) companies, IC suppliers, electronic systems designers, components suppliers, and package/printed circuit board material suppliers

Intellectual Property

6.1.a. Is the Sponsor aware of any copyright permissions needed for this project?: No

6.1.b. Is the Sponsor aware of possible registration activity related to this project?: No

7.1 Are there other standards or projects with a similar scope?: No

7.2 Joint Development

Is it the intent to develop this document jointly with another organization?: No

8.1 Additional Explanatory Notes (Item Number and Explanation): none